FORM PTO-1595 1-31-92



SHEET

U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office

Docket No.: 6192.0325.US

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof. 1. Name of conveying party(ies): 2. Name and address of receiving party(ies): Dae-Ho CHOO Name: Samsung Electronics Co., Ltd. Hak-Jin KIM 10-22-03 **Bong-Woo LEE** Internal Address: Additional names of conveying party(ies) attached? Street Address: 416, Maetan-dong, Paldal-ku yes no City: Suwon-city, Kyunggi-do State or Country: The Republic of KOREA 3. Nature of Conveyance _ Merger Additional name(s) & address(es) attached? Security Agreement Change of Name yes no Other Execution Date: August 27, 2003 4. Application number(s) or patent number(s): 40699729 Title: METHOD AND APPARATUS OF FORMING ALIGNMENT FILM If this document is being filed together with a new application, the execution date of the application is August 27, 2003 A. Patent Application No(s). filed on B. Patent No(s). Additional numbers attached? Yes No. 5. Name and address of party to whom correspondence 6. Total number of applications and patents involved: 1 concerning document should be mailed: 7. Total fee (37 CFR 3.41): \$40.00 Hae-Chan Park, Esq. McGuireWoods LLP ⊠ Enclosed 1750 Tysons Boulevard, Suite 1800 McLean, Virginia 22102 Authorized to be charged to deposit account Total fee due Any deficiencies in the enclosed fees 8. Deposit account number: 23-1951 9. Statement and signature To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Hae-Chan Park, Reg. No. 50,114 Name of Person Signing

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PATENT REEL: 014628 FRAME: 0811

ASSIGNMENT OF INVENTION

WHEREAS, I/WE, <u>Dae-Ho CHOO</u>, <u>Hak-Jin KIM</u>, <u>Bong-Woo LEE</u> has/have invented certain new and useful improvements in <u>METHOD AND APPARATUS OF FORMING ALIGNMENT FILM for which a patent application has been executed.</u>

AND WHEREAS, Samsung Electronics Co., Ltd. having a principal place of business at 416, Maetan-dong, Paldal-ku, Suwon-city, Kyunggi-do, The Republic of KOREA, referred to as Assignee, is desirous of acquiring our interest in said invention and in any Letters Patent which may be granted therefor.

NOW THIS INDENTURE WITNESSETH, That for a valuable consideration, the receipt of which is hereby acknowledged, we hereby assign, sell and transfer unto the said assignee, the entire right, title and interest in and to inventions disclosed in said application and in and to any Letters Patent of the United States and in and to any Letters Patent or Inventor's Certificates of any and all foreign countries which may be granted therefor, and in and to any and all priority and/or Convention rights or benefits accruing or to accrue to us with respect to the filing or securing of patents in the United States and/or securing of patents or inventor's certificates in any and all countries foreign thereto.

AND I/WE hereby grant to assignee the right to apply in its own name for patents or inventor's certificates corresponding to the above invention in countries foreign to the United States.

AND I/WE hereby further agree to sign and properly execute such necessary and lawful papers for application for foreign patents and inventor's certificates for filing applications for United States, foreign patents and inventor's certificates for subdivisions of any applications for patent or inventor's certificate and/or for obtaining any reissue or reissues of any Letters Patent which may be granted for our aforesaid invention and to perform such further acts as may be required to carry out the intent of this agreement as the assignee thereof shall hereafter require and prepare at assignee's expense.

PATENT REEL: 014628 FRAME: 0812

Dated: 17th Aug. 2003	CMOO DIEMO Name: Dae-Ho CHOO
Dated: 2003.0.27	Hak-Jin Kim Name: Hak-Jin KIM
Dated: 2003. P. 27	Name: Bong-Woo LEE

RECORDED: 10/22/2003

PATENT REEL: 014628 FRAME: 0813